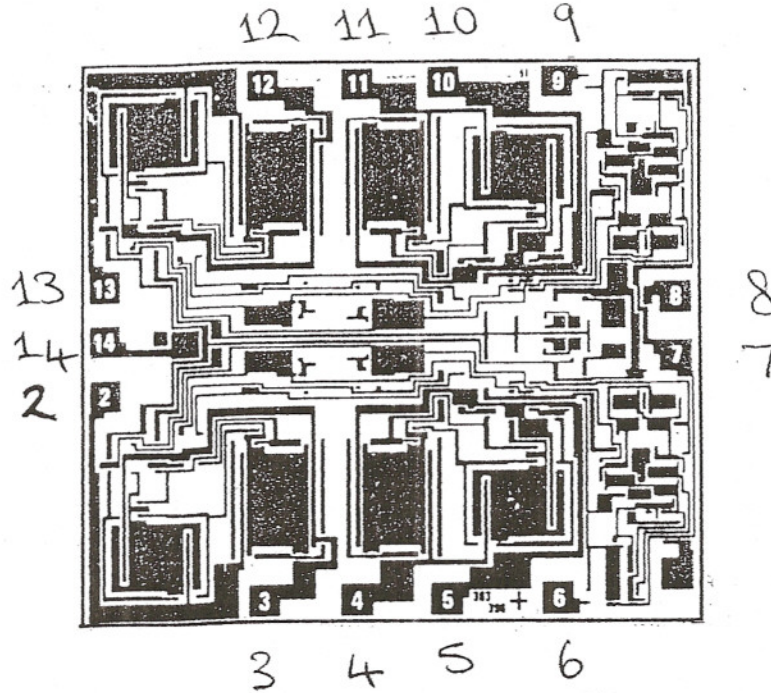




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>Pad</u>	<u>Function</u>	<u>Pad</u>	<u>Function</u>
1	NC	8	V-
2	S ₃	9	A ₂
3	D ₃	10	S ₂
4	D ₁	11	D ₂
5	S ₁	12	D ₄
6	A ₁	13	S ₄
7	GND	14	V+

Top Material: Al
Backside Material: Si
Bond Pad Size:
Backside Potential:
Mask Ref:

APPROVED BY:

DIE SIZE :.074" X .082"

DATE: 8/7/06

MFG: Harris

THICKNESS:

P/N: HI-303-2